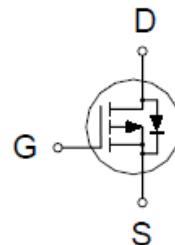
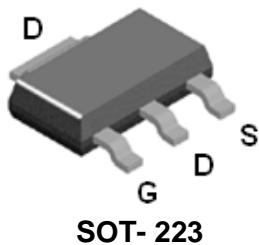


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P-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-60V	90m Ω @ $V_{GS} = 10V$	-4A



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS	SYMBOL	LIMITS	UNITS
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	I_D	-4	A
$T_A = 100^\circ C$		-2.7	
Pulsed Drain Current ²	I_{DM}	-30	
Avalanche Current	I_{AS}	-24	
Avalanche Energy	E_{AS}	30	mJ
Power Dissipation	P_D	3.125	W
$T_A = 100^\circ C$		1.25	
Operating Junction & Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	R_{0JC}	40	60	°C / W
Junction-to-Ambient	R_{0JA}			

¹Limited by Package.

²Pulse width limited by maximum junction temperature.

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ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	-60			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = -250\mu\text{A}$	-1.0	-1.7	-3.0	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 20\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = -48\text{V}, V_{\text{GS}} = 0\text{V}$			-1	μA
		$V_{\text{DS}} = -40\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			-10	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = -10\text{V}, V_{\text{GS}} = 10\text{A}$	-30			A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = -4.5\text{V}, I_D = -2\text{A}$		82	135	$\text{m}\Omega$
		$V_{\text{GS}} = -10\text{V}, I_D = -4\text{A}$		72	90	
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = -10\text{V}, I_D = -4\text{A}$		15		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = -25\text{V}, f = 1\text{MHz}$		1130		pF
Output Capacitance	C_{oss}			130		
Reverse Transfer Capacitance	C_{rss}			79		
Gate Resistance	R_g	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		4.75		Ω
Total Gate Charge ²	Q_g	$V_{\text{DS}} = 0.5V_{(\text{BR})\text{DSS}}, I_D = -4\text{A}, V_{\text{GS}} = -10\text{V}$		18		nC
Gate-Source Charge ²	Q_{gs}			6		
Gate-Drain Charge ²	Q_{gd}			4		
Turn-On Delay Time ²	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = -30\text{V}, I_D \geq -4\text{A}, V_{\text{GS}} = -10\text{V}, R_{\text{GS}} = 2.5\Omega$		10		nS
Rise Time ²	t_r			15		
Turn-Off Delay Time ²	$t_{\text{d}(\text{off})}$			27		
Fall Time ²	t_f			17		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ\text{C}$)						
Continuous Current	I_S				-2.4	A
Forward Voltage ¹	V_{SD}	$I_F = -4\text{A}, V_{\text{GS}} = 0\text{V}$			-1.3	V
Reverse Recovery Time	t_{rr}	$I_F = -4\text{A}, dI/dt = 100\text{A}/\mu\text{s}$		72		nS
Reverse Recovery Charge	Q_{rr}			127		nC

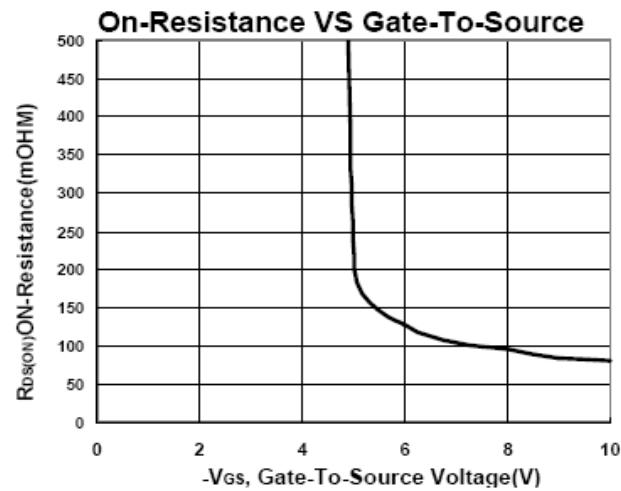
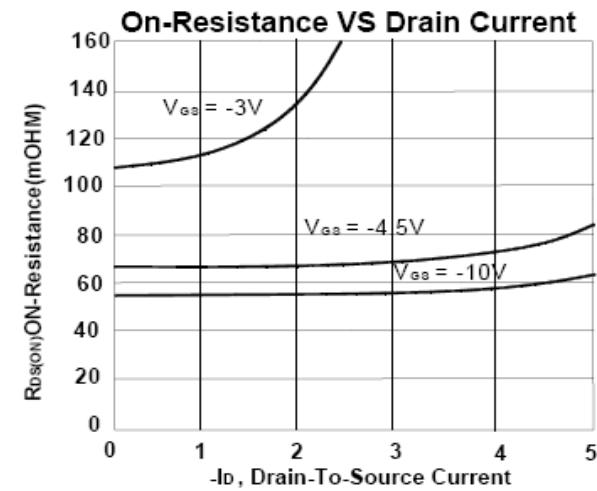
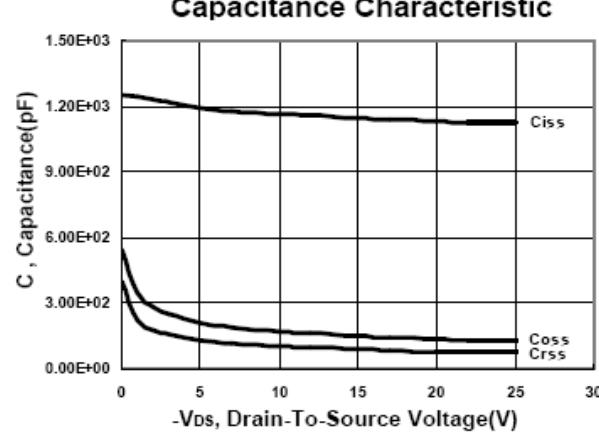
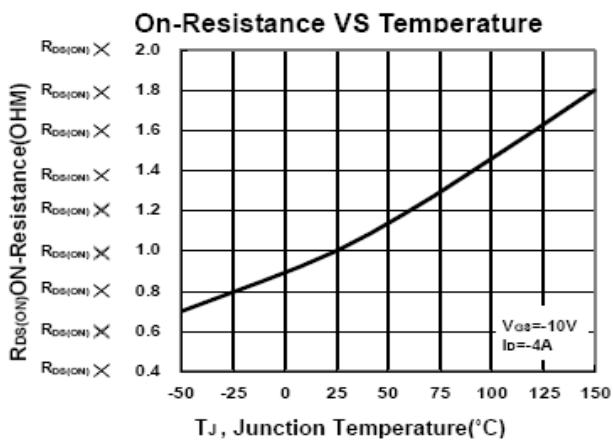
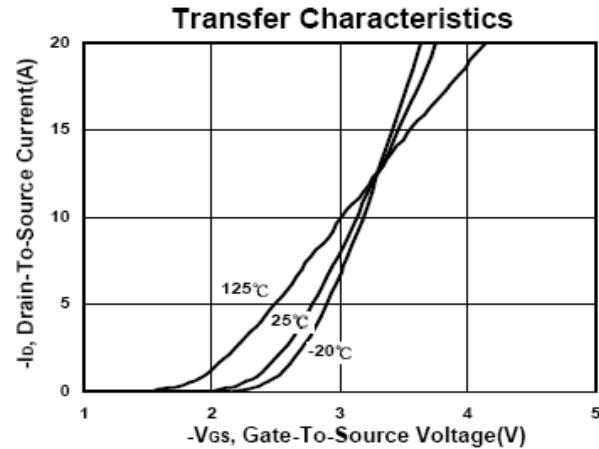
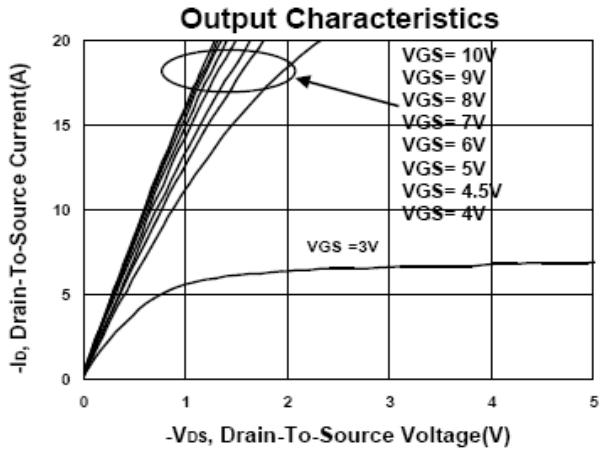
¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

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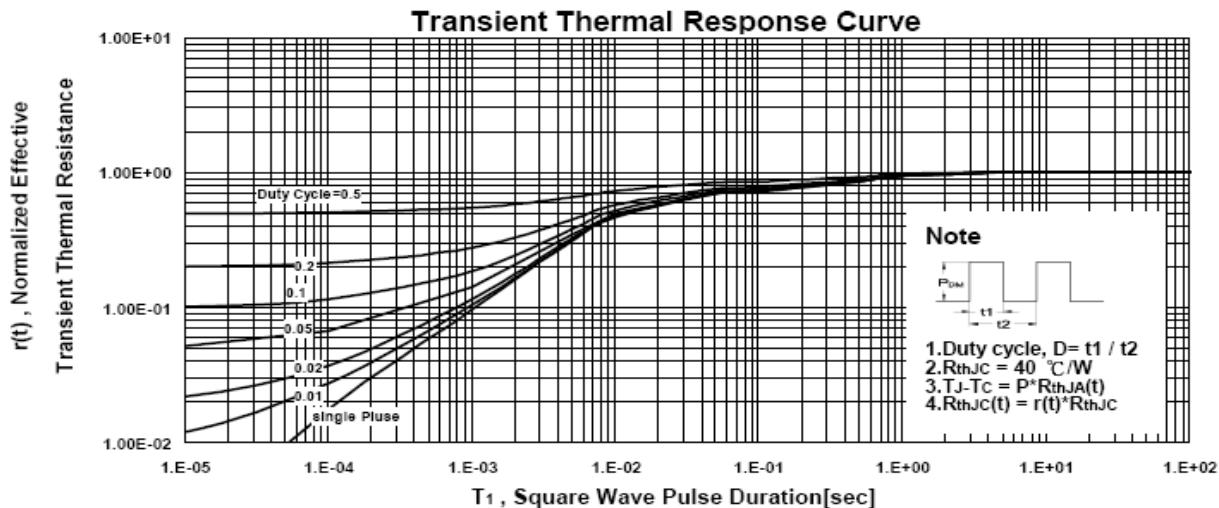
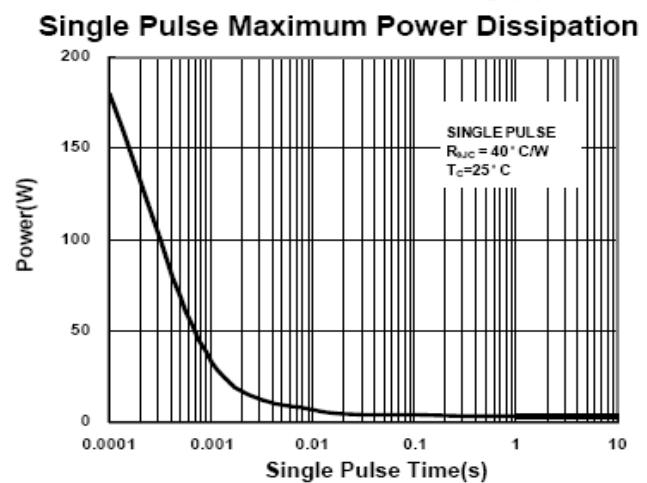
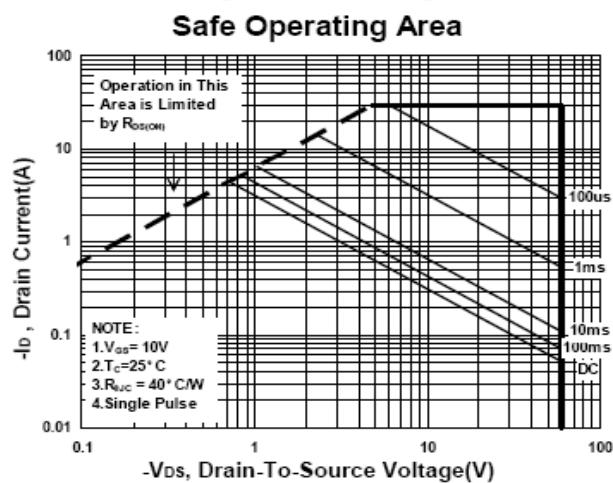
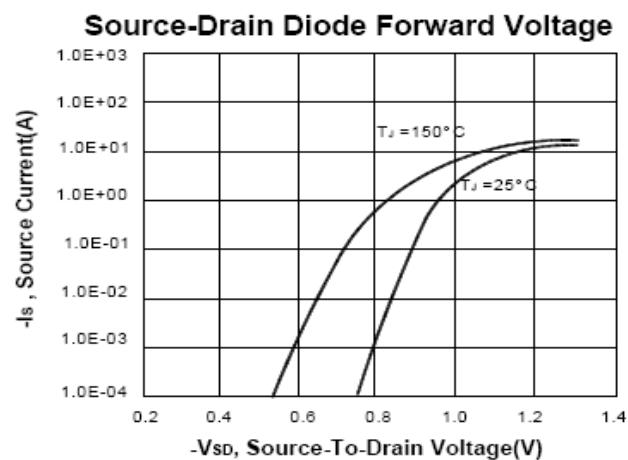
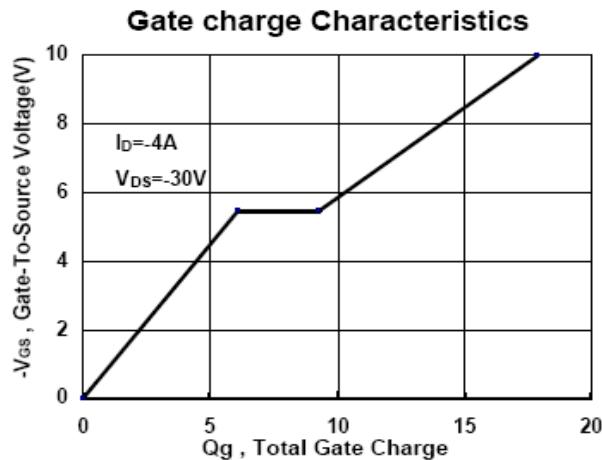
P-Channel Enhancement Mode MOSFET

TYPICAL PERFORMANCE CHARACTERISTICS P-CHANNEL



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SOT-223 MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	0.60	0.76	0.84	H	3.30	3.50	3.70
B	6.70	7.00	7.30	I	0.50	1.00	1.20
C	2.85	3.00	3.10	J	0.23	0.3	0.4
D	2.25	2.30	2.35	K	0°		10°
E	4.35	4.60	4.85	L	0	0.1	0.2
F	1.40	1.60	1.80	M			
G	6.30	6.50	6.80	N			

